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Xu et al.

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(54) **ADJUSTING EDDY CURRENT MEASUREMENTS**

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(71) Applicant: **Applied Materials, Inc.**, Santa Clara, CA (US)

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(72) Inventors: **Kun Xu**, Sunol, CA (US); **Ingemar Carlsson**, Milpitas, CA (US); **Boguslaw A. Swedek**, Cupertino, CA (US); **Doyle E. Bennett**, Santa Clara, CA (US); **Shih-Haur Shen**, Sunnyvale, CA (US); **Hassan G Iravani**, San Jose, CA (US); **Wen-Chiang Tu**, Mountain View, CA (US); **Tzu-Yu Liu**, San Jose, CA (US)

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(73) Assignee: **Applied Materials, Inc.**, Santa Clara, CA (US)

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Primary Examiner — Monica Carter

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Assistant Examiner — Marcel Dion

(74) *Attorney, Agent, or Firm* — Fish & Richardson P.C.

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(57)

ABSTRACT

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Among other things, a method of controlling polishing during a polishing process is described. The method includes receiving a measurement of a thickness, $thick(t)$, of a conductive layer of a substrate undergoing polishing from an in-situ monitoring system at a time t ; receiving a measured temperature, $T(t)$, associated with the conductive layer at the time t ; calculating resistivity ρ_T of the conductive layer at the measured temperature $T(t)$; adjusting the measurement of the thickness using the calculated resistivity ρ_T to generate an adjusted measured thickness; and detecting a polishing endpoint or an adjustment for a polishing parameter based on the adjusted measured thickness.

(52) **U.S. Cl.**
CPC **B24B 49/105** (2013.01); **B24B 37/013** (2013.01); **B24B 49/02** (2013.01); **B24B 49/14** (2013.01)

(58) **Field of Classification Search**
CPC B24B 37/013; B24B 49/02; B24B 49/105; B24B 49/14; G01B 7/105; H01L 21/67253

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19 Claims, 7 Drawing Sheets

